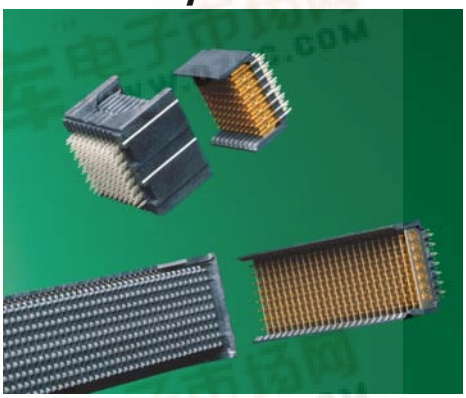
2.00 by 2.25mm (.079 by .089") Pitch VHDM® 8-Row Stacking System

75117

Board-to-Board Connector System

VHDM® Board-to-Board 8-Row Stacker System Connects High Speed, High Density for Mezzanine Boards

Molex's 8-Row VHDM Stacker system allows for 2.5 Gbps data rates with high densities on mezzanine style board-to-board applications, offering 100 real circuits per inch of connector. The VHDM Stacker system offers the flexibility of a parallel board connection using the same proven wafer design, separable interface and press-fit compliant pins as the standard VHDM connector family, with less than 5% crosstalk. VHDM Stackers are ideal for both single-ended and differential signaling.



Features and Benefits

- High speed, high density mezzanine design enables up to 2.5 Gbps bandwidth per signal pair
- 2.00 by 2.25 mm (0.79 by 0.89") pitch provides 40 contacts per centimeter
- Wafer construction permits very accurate location of ground planes relative to the signal contacts for improved impedance control
- Eye-of-the-needle press-fit receptacles and headers allow tight spacing without solder bridging between contact tails, repair ability and a highly reliable termination to the PCB
- Ground planes between signal columns provide:
  - Tightly controlled impedance for rise times down to 200 picoseconds
  - Very low cross talk between signals within a column
  - Extremely low cross talk between signal columns
- Mates with VHDM open headers permitting utilization of existing standard backplane headers

SPECIFICATIONS

Reference Information

Packaging: Tube
UL File No.: E29179
CSA File No.: 152514 (LR19980)
Mates With: 74060
Designed In: Millimeters

Electrical

Voltage: 250V
Current: 1.0A
Contact Resistance: 13.5mΩ max.
Dielectric Withstanding Voltage: 750VAC
Insulation Resistance: 500VDC

Mechanical

Contact Insertion Force: 45N max. per press-fit pin
Contact Retention to Housing: 9N min. per press-fit pin
Mating Force: 0.40N nominal per pin
Unmating Force: 0.15N min. per pin
Durability: 200 cycles

Physical

Housing: Liquid crystal polymer, UL 94V-0
Contact: Copper Alloy
Plating: Selective Gold 30µ" min. with Tin/Lead on the tails
Operating Temperature: -55 to +105° C

APPLICATIONS

- Telecommunication Equipment
- Test Systems
- High End Servers
- Memory Storage Systems
- Cellular Base Stations

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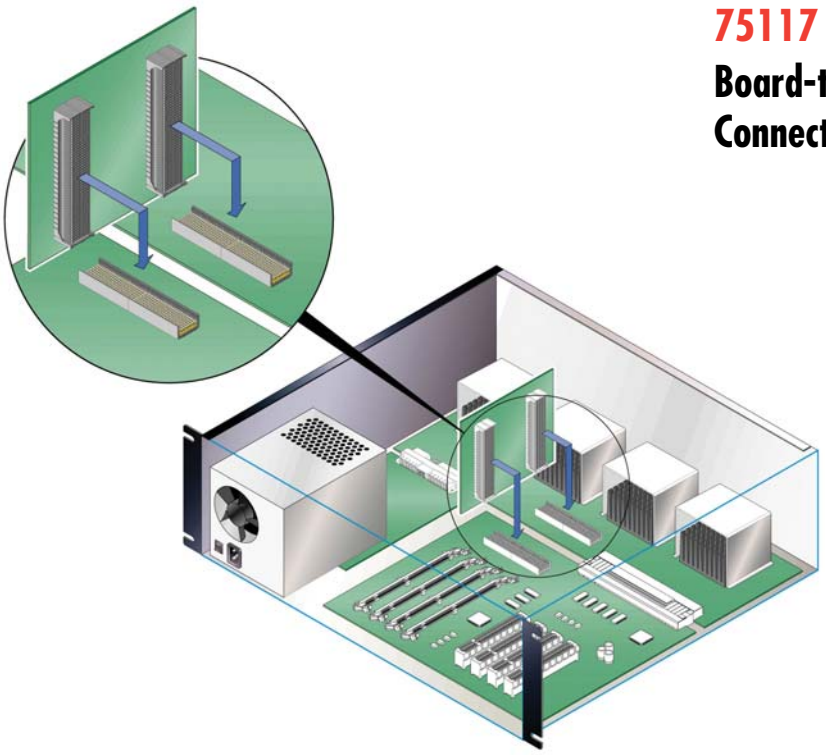

ORDERING INFORMATION

Stacker Receptacle

Order No.	Description	Circuits	Number of Wafers	Gold Plating Thickness	Stack Heights
75117-0118	VHDM 8-Row Stacker Receptacle	80	10	0.76µm (30µ")	18.00mm (.709")
75117-1118	VHDM 8-Row Stacker Receptacle	80	10	1.27µm (50µ")	
75117-0218	VHDM 8-Row Stacker Receptacle	200	25	0.76µm (30µ")	
75117-1218	VHDM 8-Row Stacker Receptacle	200	25	1.27µm (50µ")	
75117-0018	VHDM 8-Row Stacker Receptacle	400	50	0.76µm (30µ")	
75117-1018	VHDM 8-Row Stacker Receptacle	400	50	1.27µm (50µ")	

Open Header

Order No.	Description	Circuits	Module Length	Signal Pin Length
74060-1001	VHDM 8-Row Signal Module	80	20.00mm (.787")	4.75mm (.187")
74060-1002	VHDM 8-Row Signal Module	80	20.00mm (.787")	6.25mm (.246")
74060-2501	VHDM 8-Row Signal Module	200	50.00mm (1.969")	4.75mm (.187")
74060-2502	VHDM 8-Row Signal Module	200	50.00mm (1.969")	6.25mm (.246")
74060-2602	VHDM 8-Row Signal Module	200	50.00mm (1.969")	6.25mm (.246")

Americas Headquarters
Lisle, Illinois 60532 U.S.A.
1-800-78MOLEX
amerinfo@molex.com

Far East North Headquarters
Yamato, Kanagawa, Japan
81-462-65-2324
feninfo@molex.com

Far East South Headquarters
Jurong, Singapore
65-6-268-6868
fesinfo@molex.com

European Headquarters
Munich, Germany
49-89-413092-0
eurinfo@molex.com

Corporate Headquarters
2222 Wellington Ct.
Lisle, IL 60532 U.S.A.
630-969-4550
Fax:630-969-1352

Visit our Web site at www.molex.com/product/backplan/vhdm/vhdm.html

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